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(54) Title: **WAFER BOATS FOR SUPPORTING SEMICONDUCTOR WAFERS IN A FURNACE**

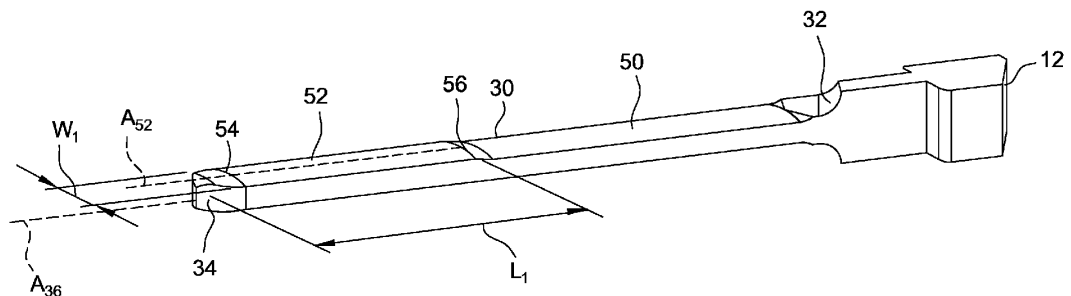


FIG. 3

(57) Abstract: A wafer boat for supporting a plurality of semiconductor wafers in a furnace. The wafer boat includes a set of fingers each having a contact protuberance which contacts and supports a semiconductor wafer.

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